



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-01-25
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CDO7*3078BH6	A	BO2A	2018-01-25
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	Package: O7 SO 08 .15 JEDEC; MDF valid for MC33078DT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CDO7*3078BH6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.571	mg	supplier	die	Silicon (Si)	7440-21-3		1.543	mg	982177	19288
				supplier	metallization	Aluminium (Al)	7429-90-5		0.013	mg	8275	163
				supplier	Passivation	Silicon Nitride	12033-89-5		0.007	mg	4456	88
				supplier	Passivation	Silicon Oxide	7631-86-9		0.008	mg	5092	100
				supplier	alloy	Copper (Cu)	7440-50-8		30.072	mg	991559	375900
Leadframe	Copper & its alloys	30.328	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	495	188
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.024	mg	791	300
				supplier	metallization	Silver (Ag)	7440-22-4		0.217	mg	7155	2713
				supplier	glue	Silver (Ag)	7440-22-4		0.518	mg	875000	6475
Die attach	Other Organic Materials	0.592	mg	supplier	glue	Isobornyl Methacrylate	7534-94-3		0.030	mg	50676	375
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.030	mg	50676	375
				supplier	glue	Acrylate polymer	87320-05-6		0.012	mg	20270	150
				supplier	glue	Epoxyoctahydroxyethyldimethoxysilane	3388-04-3		0.001	mg	1689	13
				supplier	glue	tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	1689	13
Bonding wires	Other inorganic materials	0.065	mg	supplier	wire	Copper (Cu)	7440-50-8		0.065	mg	1000000	813
Encapsulation	Other Organic Materials	46.386	mg	supplier	mold compound	Silica, vitreous	60676-86-0		40.170	mg	865994	502125
				supplier	mold compound	Epoxy Resin	25068-38-6		3.479	mg	75001	43488
				supplier	mold compound	Phenol Resin	29690-82-2		2.319	mg	49994	28988
				supplier	mold compound	Carbon black	1333-86-4		0.232	mg	5002	2900
connections coating	Solder	1.058	mg	supplier	mold compound	Bismuth compound	7440-69-9		0.186	mg	4010	2325
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.058	mg	1000000	13225